

cancelled. Claims 11-12 are amended, and claim 21 is added. Reconsideration based on the above amendments and following remarks is respectfully requested.

In response to the telephone Restriction Requirement on November 22, 2002, Applicant affirms the election of Group II, claims 11-20. This election is made with traverse.

It is respectfully submitted that the subject matter of all claims 1-21 is sufficiently related that a thorough search for the subject matter of any one Group of claims would encompass a search for the subject matter of the remaining claims. Thus, it is respectfully submitted that the search and examination of the entire application could be made without serious burden. See MPEP §803 in which it is stated that "if the search and examination of an entire application can be made without serious burden, the examiner must examine it on the merits, even though it includes claims to independent or distinct inventions" (emphasis added). It is respectfully submitted that this policy should apply in the present application in order to avoid unnecessary delay and expense to Applicant and duplicative examination by the Patent Office.

Thus, withdrawal of the Restriction Requirement is respectfully requested.

**I. The Abstract and Title Satisfy All Formal Requirements**

The Abstract and Title are objected to because they are no longer descriptive of the elected invention. Accordingly, the Title and Abstract are amended. Withdrawal of the objection to the Title and Abstract is respectfully requested.

**II. Claims 19 and 20 Satisfy All Formal Requirements**

Claims 19 and 20 are objected to as being of improper dependent form. Applicant respectfully disagrees with this assertion. Claim 19 further recites that there are a plurality of the three-dimensional mounting assemblies and further, an optical fiber is connected to each of the three-dimensional mounting assemblies. With respect to claim 20, claim 20 further recites that a plug is electrically connected to each of the three-dimensional mounting

assemblies. Accordingly, claims 19 and 22 further limit the subject matter of the previous claim. Withdrawal of the objection to claims 19 and 20 is respectfully requested.

### **III. The Claims Define Allowable Subject Matter**

The Office Action rejects claims 11-20 under 35 U.S.C. §103(a) as unpatentable over U.S. Patent No. 5,522,002 to Chun et al. in view of U.S. Patent No. 5,337,388 to Jacobowitz. This rejection is respectfully traversed.

Neither Chun nor Jacobowitz teach, disclose or suggest the interconnections having a first exposed surface level with a first side of the molded body and wherein the interconnections have a second exposed surface level with a second side of the molded body differing from the first side, as claimed in claim 11. Additionally, the applied art does not disclose an interconnection having an exposed surface formed by a mold by which a side of a molded body is formed, as claimed in claim 21.

Instead, Chun discloses a method for making an optical interface unit with a detachable photonic device. Interconnect module 201 includes an interconnect substrate 202 having a plurality of electrical traces 203, standard electric components such as IC's 207 and 208, electrical leads 210 and a molded portion 217 having a surface 218. Additionally, there is an electrical interface connection 214 between the inner workings of interconnect module 201 and a plurality of contacts 205. Electrical leads 210 are made by any suitable method to any suitable form, such as lead member frame 211, pins 213, conductive bumps 212 to provide a path for electrical signals to be able to be inputted and outputted from the interconnect module 201. End surface 218 and surface 217 are made having several portions removed to make openings 221 and 226 such as slots or grooves to expose contacts 222 and 224. The openings 221 allow access to contact 222 with electrical connection to the inner workings of interconnect substrate 202 by wire bond 223. As such, Chun does not disclose the features recited in claims 11 and 21.

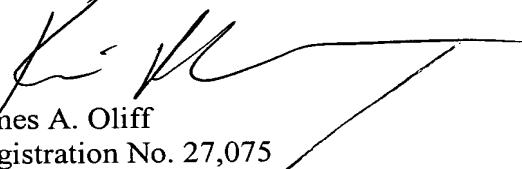
Therefore, Applicant submits that for at least the reasons discussed above, independent claims 11 and 21 define patentable subject matter. The claims that depend from claim 11 are like distinguishable over the applied art for at least the reasons discussed, as well as for the additional features they recite. Withdrawal of the rejection of the claims under 35 U.S.C. §103 is respectfully requested.

**IV. Conclusion**

In view of the foregoing amendments and remarks, Applicants submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,

  
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Attachments:

Appendix  
Substitute Abstract

Date: March 10, 2003

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**DEPOSIT ACCOUNT USE  
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## APPENDIX

## Changes to Title:

The following is a marked-up version of the amended title:

THREE-DIMENSIONAL MOUNTED ASSEMBLY, ~~METHOD OF MANUFACTURING  
THE SAME,~~ AND OPTICAL TRANSMISSION DEVICE

## Changes to Abstract:

The following is a marked-up version of the amended Abstract.

A method of manufacturing a three-dimensional mounted assembly includes steps of disposing a molded body, a plurality of electronic parts ~~on a mold~~, providing sealed with the molded body, a plurality of interconnections ~~on the mold by adhering them~~, sealing the electronic parts and the interconnections with a molding material, processing the surface shape of the molding material by the mold three-dimensionally, curing the molding material, and removing the mold from the molding material electrically connected to the electronic parts and sealed with the molded body wherein part of at least one of the interconnections is exposed on a first side of the molded body and at least another one of the interconnections is exposed on a second side of the molded body differing from the first side.

## Changes to Claims:

Claims 13-16 are canceled.

The following is a marked-up version of the amended claims:

11. (Amended) A three-dimensional mounted assembly comprising:

a molded body;

a plurality of electronic parts sealed with the molded body; and

a plurality of interconnections electrically connected to the electronic parts and sealed with the molded body,

wherein part of at least one of the interconnections is have a first exposed on-surface level with a first side of the molded body, and

wherein part of at least another one of the interconnections is have a second exposed on-surface level with a second side of the molded body differing from the first side.

12. (Amended) The three-dimensional mounted assembly as defined in claim 11,  
~~wherein the molded body is a rectangular parallelepiped, and~~  
~~wherein the exposed portions of the interconnections are disposed on a plurality of the sides of the molded body~~the interconnections have third exposed surfaces, every side except the first and second sides of the molded body is level with one of the third exposed surfaces.

Claim 21 is added.